

LM49100 Boomer[®] Audio Power Amplifier Series Mono Class AB Audio Sub-System with a True-Ground **Headphone Amplifier**

General Description

The LM49100 is a fully integrated audio subsystem capable of delivering 1.275W of continuous average power into a mono 8Ω bridged-tied load (BTL) with 1% THD+N and with a 5V power supply. The LM49100 also has a stereo true-ground headphone amplifier capable of 50mW per channel of continuous average power into a 32Ω single-ended (SE) loads with 1% THD+N.

The LM49100 has three input channels. One pair of SE inputs can be used with a stereo signal. The other input channel is fully differential and may be used with a mono input signal. The LM49100 features a 32-step digital volume control and ten distinct output modes. The mixer, volume control, and device mode select are controlled through an I²C compatible interface.

Thermal overload protection prevent the device from being damaged during fault conditions. Superior click and pop suppression eliminates audible transients on power-up/down and during shutdown.

Key Specifications

Power Output at V _{DD} = 5V:	
Loudspeaker (LS):	
R_L = 8Ω, THD+N ≤ 1%	1.275W
Headphone ($V_{DD}HP = 2.8V$):	
$R_L = 32\Omega$, THD+N $\leq 1\%$	50mW
Shutdown current	0.01µA

Shutdown current

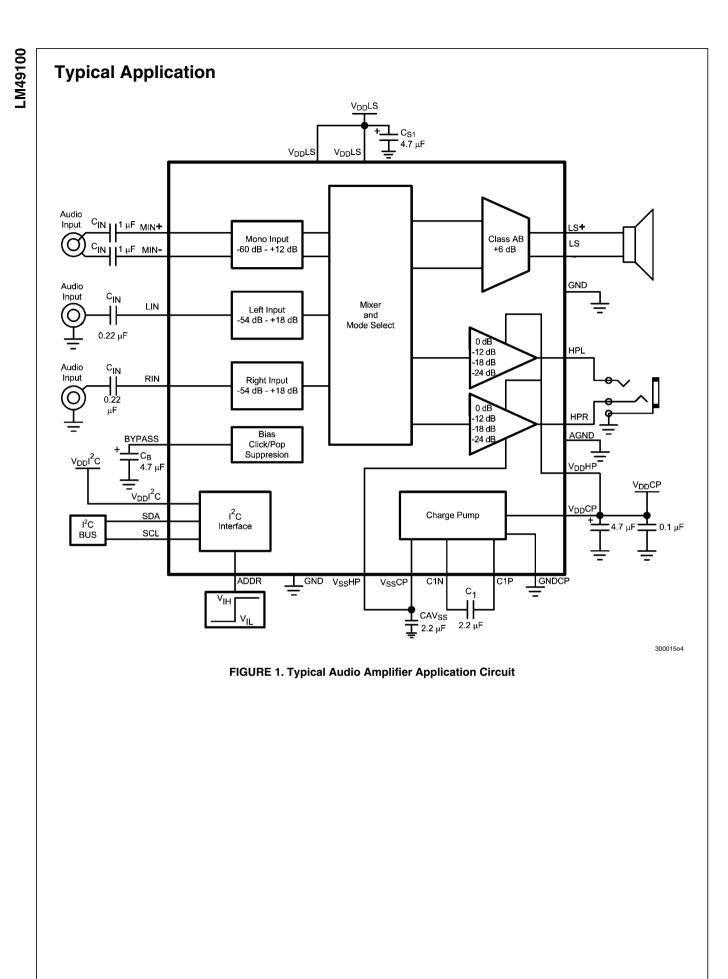
Features

- Mono and stereo inputs
- **Thermal Overload Protection**
- **True-ground Headphone Drivers**
- I²C Control Interface
- Input mute attenuation
- 2nd Stage headphone attenuator
- 32-step digital volume control
- 10 Operating Modes
- Minimum external components
- Click and Pop suppression
- -Micro-power shutdown
- Available in space-saving 3mm x 3mm 25 bump GR package
- **RF** Suppression

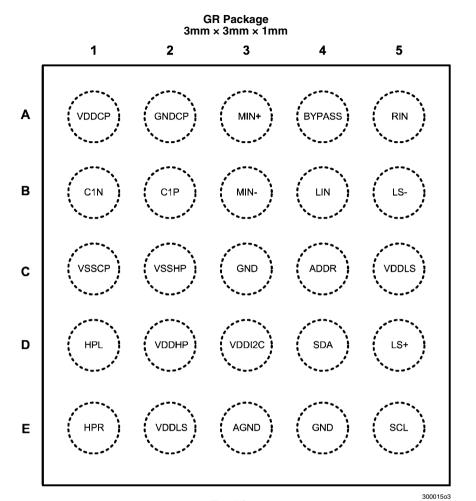
Applications

- Mobile Phones
- PDAs
- Laptops
- **Portable Electronics**

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Connection Diagrams



Top View Order Number LM49100GR See NS Package Number GRA25A

GR Package Marking

XYTT GC9	
	300015f6



Bump Descriptions	
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A1 $V_{DD}CP$ Positive Charge Pump Power SupplyA2GNDCPCharge Pump GroundA3MIN+Positive Mono InputA4BYPASSHalf-Supply BypassA5RINRight InputB1C1NNegative Terminal – Charge Pump Flying CapacitorB2C1PPositive Terminal – Charge Pump Flying CapacitorB3MIN-Negative Mono InputB4LINLeft InputB5LS-Negative Charge Pump Power SupplyC1V _{SS} CPNegative Charge Pump Power SupplyC2V _{SS} HPNegative Headphone Power SupplyC3GNDGroundC4ADDRI/C Address IdentificationC5V _{DD} LSLoudspeaker Power SupplyD1HPLLeft Headphone OutputD2V _{DD} HPPositive Headphone Power SupplyD3V _{DD} I2CI/C Power SupplyD4SDAI/C DataD5LS+Loudspeaker Output PositiveE1HPRRight Headphone OutputE2V _{DD} LSLoudspeaker Power SupplyE3AGNDHeadphone OutputE4GNDGround	-	Neme	
A2 GNDCP Charge Pump Ground A3 MIN+ Positive Mono Input A4 BYPASS Half-Supply Bypass A5 RIN Right Input B1 C1N Negative Terminal – Charge Pump Flying Capacitor B2 C1P Positive Terminal – Charge Pump Flying Capacitor B3 MIN- Negative Mono Input B4 LIN Left Input B5 LS- Negative Charge Pump Power Supply C1 V _{SS} CP Negative Charge Pump Power Supply C2 V _{SS} HP Negative Headphone Power Supply C3 GND Ground C4 ADDR I/2 Address Identification C5 V _{DD} LS Loudspeaker Power Supply D1 HPL Left Headphone Power Supply D1 HPL Left Headphone Power Supply D3 V _{DD} I ² C I ² C Power Supply D4 SDA I ² C Data D5 LS+ Loudspeaker Output Positive E1 HPR Right Headphone Output E2 V _{DD} LS Loudspeaker Power Supply	Bump	Name	Description
A3 MIN+ Positive Mono Input A4 BYPASS Half-Supply Bypass A5 RIN Right Input B1 C1N Negative Terminal – Charge Pump Flying Capacitor B2 C1P Positive Terminal – Charge Pump Flying Capacitor B3 MIN- Negative Mono Input B4 LIN Left Input B5 LS- Negative Loudspeaker Output C1 V _{SS} CP Negative Headphone Power Supply C2 V _{SS} HP Negative Headphone Power Supply C3 GND Ground C4 ADDR I²C Address Identification C5 V _{DD} LS Loudspeaker Power Supply D1 HPL Left Headphone Output D2 V _{DD} HP Positive Headphone Power Supply D3 V _{DD} I²C I²C Power Supply D4 SDA I²C Data D5 LS+ Loudspeaker Output Positive E1 HPR Right Headphone Output E2 V _{DD} LS Loudspeaker Power Supply D4 SDA I²C Data <			
A4 BYPASS Half-Supply Bypass A5 RIN Right Input B1 C1N Negative Terminal – Charge Pump Flying Capacitor B2 C1P Positive Terminal – Charge Pump Flying Capacitor B3 MIN- Negative Mono Input B4 LIN Left Input B5 LS- Negative Loudspeaker Output C1 V _{SS} CP Negative Charge Pump Power Supply C2 V _{SS} HP Negative Headphone Power Supply C3 GND Ground C4 ADDR I²C Address Identification C5 V _{DD} LS Loudspeaker Power Supply D1 HPL Left Headphone Output D2 V _{DD} HP Positive Headphone Power Supply D3 V _{DD} IP Positive Headphone Power Supply D4 SDA I²C Data D5 LS+ Loudspeaker Output Positive E1 HPR Right Headphone Output E2 V _{DD} LS Loudspeaker Output Positive E1 HPR Right Headphone Output E2 V _{DD} LS Loudspeaker Pow	A2	GNDCP	
A5 RIN Right Input B1 C1N Negative Terminal – Charge Pump Flying Capacitor B2 C1P Positive Terminal – Charge Pump Flying Capacitor B3 MIN- Negative Mono Input B4 LIN Left Input B5 LS- Negative Loudspeaker Output C1 V _{SS} CP Negative Charge Pump Power Supply C2 V _{SS} HP Negative Headphone Power Supply C3 GND Ground C4 ADDR I2C Address Identification C5 V _{DD} LS Loudspeaker Power Supply D1 HPL Left Headphone Output D2 V _{DD} HP Positive Headphone Power Supply D3 V _{DD} IPC I2C Power Supply D4 SDA I2C Data D5 LS+ Loudspeaker Output Positive E1 HPR Right Headphone Output E2 V _{DD} LS Loudspeaker Output Positive E3 AGND Headphone Output E4 GND Ground	A3	MIN+	
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B4 LIN Left Input B5 LS- Negative Loudspeaker Output C1 V _{SS} CP Negative Charge Pump Power Supply C2 V _{SS} HP Negative Headphone Power Supply C3 GND Ground C4 ADDR I²C Address Identification C5 V _{DD} LS Loudspeaker Power Supply D1 HPL Left Headphone Output D2 V _{DD} HP Positive Headphone Power Supply D3 V _{DD} I ² C I²C Power Supply D4 SDA I²C Data D5 LS+ Loudspeaker Output Positive E1 HPR Right Headphone Output E2 V _{DD} LS Loudspeaker Power Supply E3 AGND Headphone Output E4 GND Ground	B2	C1P	Positive Terminal – Charge Pump Flying Capacitor
B5LS-Negative Loudspeaker OutputC1 $V_{SS}CP$ Negative Charge Pump Power SupplyC2 $V_{SS}HP$ Negative Headphone Power SupplyC3GNDGroundC4ADDRI²C Address IdentificationC5 $V_{DD}LS$ Loudspeaker Power SupplyD1HPLLeft Headphone OutputD2 $V_{DD}HP$ Positive Headphone Power SupplyD3 $V_{DD}I^{2}C$ I²C Power SupplyD4SDAI²C DataD5LS+Loudspeaker Output PositiveE1HPRRight Headphone OutputE2 $V_{DD}LS$ Loudspeaker Power SupplyE3AGNDHeadphone Signal Ground (See Application Information section).E4GNDGround	B3	MIN-	Negative Mono Input
C1V _{SS} CPNegative Charge Pump Power SupplyC2V _{SS} HPNegative Headphone Power SupplyC3GNDGroundC4ADDRI²C Address IdentificationC5V _{DD} LSLoudspeaker Power SupplyD1HPLLeft Headphone OutputD2V _{DD} HPPositive Headphone Power SupplyD3V _{DD} I²CI²C Power SupplyD4SDAI²C DataD5LS+Loudspeaker Output PositiveE1HPRRight Headphone OutputE2V _{DD} LSLoudspeaker Power SupplyE3AGNDHeadphone Signal Ground (See Application Information section).E4GNDGround	B4	LIN	Left Input
C2V _{SS} HPNegative Headphone Power SupplyC3GNDGroundC4ADDRI²C Address IdentificationC5V _{DD} LSLoudspeaker Power SupplyD1HPLLeft Headphone OutputD2V _{DD} HPPositive Headphone Power SupplyD3V _{DD} I²CI²C Power SupplyD4SDAI²C DataD5LS+Loudspeaker Output PositiveE1HPRRight Headphone OutputE2V _{DD} LSLoudspeaker Power SupplyE3AGNDHeadphone Signal Ground (See Application Information section).E4GNDGround	B5	LS–	Negative Loudspeaker Output
C3GNDGroundC4ADDRI²C Address IdentificationC5V _{DD} LSLoudspeaker Power SupplyD1HPLLeft Headphone OutputD2V _{DD} HPPositive Headphone Power SupplyD3V _{DD} I²CI²C Power SupplyD4SDAI²C DataD5LS+Loudspeaker Output PositiveE1HPRRight Headphone OutputE2V _{DD} LSLoudspeaker Power SupplyE3AGNDHeadphone Signal Ground (See Application Information section).E4GNDGround	C1	V _{SS} CP	Negative Charge Pump Power Supply
C4ADDRI²C Address IdentificationC5V _{DD} LSLoudspeaker Power SupplyD1HPLLeft Headphone OutputD2V _{DD} HPPositive Headphone Power SupplyD3V _{DD} I²CI²C Power SupplyD4SDAI²C DataD5LS+Loudspeaker Output PositiveE1HPRRight Headphone OutputE2V _{DD} LSLoudspeaker Power SupplyE3AGNDHeadphone Signal Ground (See Application Information section).E4GNDGround	C2	V _{SS} HP	Negative Headphone Power Supply
C5V _{DD} LSLoudspeaker Power SupplyD1HPLLeft Headphone OutputD2V _{DD} HPPositive Headphone Power SupplyD3V _{DD} I ² CI ² C Power SupplyD4SDAI ² C DataD5LS+Loudspeaker Output PositiveE1HPRRight Headphone OutputE2V _{DD} LSLoudspeaker Power SupplyE3AGNDHeadphone Signal Ground (See Application Information section).E4GNDGround	C3	GND	Ground
D1 HPL Left Headphone Output D2 V _{DD} HP Positive Headphone Power Supply D3 V _{DD} I ² C I ² C Power Supply D4 SDA I ² C Data D5 LS+ Loudspeaker Output Positive E1 HPR Right Headphone Output E2 V _{DD} LS Loudspeaker Power Supply E3 AGND Headphone Signal Ground (See Application Information section). E4 GND Ground	C4	ADDR	I ² C Address Identification
D2VPositive Headphone Power SupplyD3VI²C Power SupplyD4SDAI²C DataD5LS+Loudspeaker Output PositiveE1HPRRight Headphone OutputE2VLoudspeaker Power SupplyE3AGNDHeadphone Signal Ground (See Application Information section).E4GNDGround	C5	V _{DD} LS	Loudspeaker Power Supply
D3 V _{DD} I ² C I ² C Power Supply D4 SDA I ² C Data D5 LS+ Loudspeaker Output Positive E1 HPR Right Headphone Output E2 V _{DD} LS Loudspeaker Power Supply E3 AGND Headphone Signal Ground (See Application Information section). E4 GND Ground	D1	HPL	Left Headphone Output
D4 SDA I ² C Data D5 LS+ Loudspeaker Output Positive E1 HPR Right Headphone Output E2 V _{DD} LS Loudspeaker Power Supply E3 AGND Headphone Signal Ground (See Application Information section). E4 GND Ground	D2	V _{DD} HP	Positive Headphone Power Supply
D5 LS+ Loudspeaker Output Positive E1 HPR Right Headphone Output E2 V _{DD} LS Loudspeaker Power Supply E3 AGND Headphone Signal Ground (See Application Information section). E4 GND Ground	D3	V _{DD} I ² C	I ² C Power Supply
E1 HPR Right Headphone Output E2 V _{DD} LS Loudspeaker Power Supply E3 AGND Headphone Signal Ground (See Application Information section). E4 GND Ground	D4	SDA	I ² C Data
E2 V _{DD} LS Loudspeaker Power Supply E3 AGND Headphone Signal Ground (See Application Information section). E4 GND Ground	D5	LS+	Loudspeaker Output Positive
E3 AGND Headphone Signal Ground (See Application Information section). E4 GND Ground	E1	HPR	Right Headphone Output
E4 GND Ground	E2	V _{DD} LS	Loudspeaker Power Supply
	E3	AGND	Headphone Signal Ground (See Application Information section).
	E4	GND	Ground
E5 SCL I ² C Clock	E5	SCL	I ² C Clock

Absolute Maximum Ratings (Notes 1, 2)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/ Distributors for availability and specifications.

Thermal Resistance θ_{JA} (GR)

50.2°C/W

Operating Ratings

Temperature Range

Supply Voltage (Loudspeaker)Supply Voltage (Headphone)Storage Temperature-65°C toInput Voltage-0.3V to V _{DI} Power Dissipation (Note 3)ESD Susceptibility (Note 4)ESD Susceptibility (Note 5)Junction Temperature	_D + 0.3V	Temperature Range $T_{MIN} \le T_A \le T_{MAX}$ Supply Voltage V _{DD} LS Supply Voltage V _{DD} HP I ² C Voltage (V _{DD} I ² C)	$-40^{\circ}C \le T_A \le +85^{\circ}C$ $2.7V \le V_{DD}LS \le 5.5V$ $2.4V \le V_{DD}HP \le 2.9V$ $1.7V \le V_{DD}HP \le V_{DD}LS$ $V_{DD}HP \le V_{DD}LS$ $V_{DD}I^2C \le V_{DD}LS$
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Electrical Characteristics V_{DD}LS = 3.6V, V_{DD}HP = 2.8V (Notes 1, 2)

The following specifications apply for all programmable gain set to 0 dB, $C_B = 4.7 \mu$ F, $R_{L (SP)} = 8\Omega$, $R_{L(HP)} = 32\Omega$, f = 1 kHz unless otherwise specified. Limits apply for $T_A = 25^{\circ}$ C.

						LM49100		
Symbol Parameter		Conditions			Typical (Note 6)	Limit (Note 7)	Units (Limits)	
			Modes 1, 3, 5 V _{IN} = 0V, No Lo	ad	2.9		mA	
		$V_{DD}LS = 3.0V$ $V_{DD}HP = 2.8V$		ad	3.4		mA	
			Modes 7, 10, 14 V _{IN} = 0V, No Lo		4.8		mA	
			Modes 1, 3, 5 V _{IN} = 0V, No Lo	ad	2.9	4.3	mA (max	
l _{DD}	Supply Current	$V_{DD}LS = 3.6V$ $V_{DD}HP = 2.8V$	Modes 2, 4, 6 V _{IN} = 0V, No Lo	ad	3.5	5.4	mA (max)	
			Modes 7, 10, 14 V _{IN} = 0V, No Lo		4.8	7.4	mA (max	
			Modes 1, 3, 5 V _{IN} = 0V, No Lo	/lodes 1, 3, 5 / _{IN} = 0V, No Load			mA	
		$V_{DD}LS = 5.0V$ $V_{DD}HP = 2.8V$	Modes 2, 4, 6 V _{IN} = 0V, No Load		3.6		mA	
			Modes 7, 10, 14 V _{IN} = 0V, No Lo		5.0		mA	
SD	Shutdown Supply Current	Mode 0			0.01	1	µA (max)	
		V _{IN} = 0V, Mode	7, Mono		6.0	25	mV (max	
		V _{IN} = 0V, Mode	7, Headphone C	Gain = –24dB	2.2	5.5	mV	
V _{os}	Output Offset Voltage	V _{IN} = 0V, Mode	$V_{IN} = 0V$, Mode 7, Headphone Gain = -18 dB				mV (max	
		V _{IN} = 0V, Mode	$V_{IN} = 0V$, Mode 7, Headphone Gain = $-12dB$				mV	
		V _{IN} = 0V, Mode	7, Headphone C	Gain = 0dB	7	15	mV (max	
			LS f = 1kHz	R _L = 8Ω 1% 10%	425 525		mW mW	
P _{OUT}	Output Power	$V_{DD}LS = 3.0V$	HP	R _L = 16Ω 1% 10%	49 69		mW mW	
			f = 1kHz	R _L = 32Ω 1% 10%	35 44		mW mW	

					LM49100		
Symbol	Parameter		Conditions			Limit (Note 7)	Units (Limits)
			LS f = 1kHz	R _L = 8Ω 1% 10%	640 790	600	mW (min mW
P _{OUT}	Output Power	V _{DD} LS = 3.6V	НР	R _L = 16Ω 1% 10%	49 72		mW mW
			f = 1kHz	R _L = 32Ω 1% 10%	50 62	46	mW (min mW
			LS f = 1kHz	R _L = 8Ω 1% 10%	1275 1575		mW mW
P _{OUT}	Output Power	$V_{DD}LS = 5.0V$	HP f = 1kHz	R _L = 16Ω 1% 10%	49 72		mW mW
				R _L = 32Ω 1% 10%	53 62		mW mW
	Total Harmonic Distortion +	V _{DD} LS = 3.0V	f = 1kHz	Loudspeaker; Mode 1, $R_L = 8\Omega$, $P_{OUT} = 215$ mW	0.05		%
THD+N	Noise			Headphone; Mode 4, R_L = 32Ω , P_{OUT} = 25mW	0.02		%
	Total Harmonic Distortion +	V. 10. 00V		Loudspeaker; Mode 1, R_L = 8Ω , P_{OUT} = 320mW	0.05		%
THD+N	Noise	V _{DD} LS = 3.6V	f = 1kHz	Headphone; Mode 4, R_L = 32Ω , P_{OUT} = 25mW	0.02		%
THD+N	Total Harmonic Distortion +		f = 1kHz	Loudspeaker; Mode 1, R _L = 8Ω , P _{OUT} = 630mW	0.035		%
	Noise	$V_{DD}LS = 5.0V$		Headphone; Mode 4, R_L = 32Ω , P_{OUT} = 25mW	0.02		%

					LM4	11	
Symbol	Symbol Parameter Conc				Typical (Note 6)	Limit (Note 7)	Units (Limits)
					Headph	none	
				Mode 2,10	12		μV
				Mode 4, 7	13		μV
		A-weighted, 0 d	dB. inputs	Mode 6, 14	16		μν
e _N	Noise	terminated to G	-		Loudspe	eaker	
		referred		Mode 1	14		μV
				Mode 3, 7, 10, 14	23		μV
				Mode 5	27		μV
T _{ON}	Turn-on Time			•	26		ms
T _{OFF}	Turn-off Time				1		ms
		Maximum gain	setting		12.5	10 15	kΩ (min) kΩ (max)
Z _{IN}	Input Impedance	Maximum atter	nuation setting		110	90 130	kΩ (min) kΩ (max
		Stereo (Left and Right Channels) Input referred maximum attenuation		maximum	-54	_52 _56	dB (min)
A _v Vo				maximum gain	18	17.5 18.5	dB (min) dB (max
	Volume Control	Input referred attenuation		maximum	-60	-58 -62	dB (min) dB (max
		Mono Input referred maximum g			12	11.5 12.5	dB (min) dB (max
		Headphone Mc V _{CM} = 1 V _{PP} ,R _L		z,	64	12.0	dB
CMRR	Common Mode Rejection Ratio			Hz, $V_{CM} = 1 V_{PP}$,	58		dB
			Vpp on Vpp I S	, output referred, i	nouts termin	i ated to GND	f = 217Hz
		LS, Mode 1		,	90		dB
PSRR	Power Supply Rejection Ratio	LS, Mode 3, 7,	10.14		78		dB
		LS, Mode 5	-,		70		dB
			Vpp on Vpp HF	P, output referred,		nated to GND	
PSRR	Power Supply Rejection Ratio	LS, Mode 7, 10		,	83		dB
				, output referred, i		ated to GND	
		HP, Mode 2, 10			90		dB
PSRR	Power Supply Rejection Ratio	HP, Mode 2, 10 HP, Mode 4, 7			88		dB
		HP, Mode 4, 7 HP, Mode 6, 14			87		dB
				P, output referred,		L nated to GND	
		HP, Mode 2, 10		,	83		dB
PSRR	Power Supply Rejection Ratio	HP, Mode 2, 10 HP, Mode 4, 7	,		83		dB
		HP, Mode 4, 7 HP, Mode 6, 14			80		dB

-M49100

12C (Notes 2, 7)

The following specifications apply for V_{DD} = 5.0V and 3.3V, T_A = 25°C, 2.2V \leq V_{DD}I²C \leq 5.5V, unless otherwise specified.

Symbol	Parameter	Conditions (Note 8)	LN	LM49100		
			Typical (Note 6)	Limits (Note 7)	(Limits)	
t ₁	I ² C Clock Period			2.5	µs (min)	
t ₂	I ² C Data Setup Time			100	ns (min)	
t ₃	I ² C Data Stable Time			0	ns (min)	
t ₄	Start Condition Time			100	ns (min)	
t ₅	Stop Condition Time			100	ns (min)	
t ₆	I ² C Data Hold Time			100	ns (min)	
V _{IH}	I ² C Input Voltage High			0.7xV _{DD} I ² C	V (min)	
V _{IL}	I ² C Input Voltage Low			0.3xV _{DD} I ² C	V (max)	

I²**C** (Notes 2, 7)

The following specifications apply for V_{DD} = 5.0V and 3.3V, T_A = 25°C, 1.7V ≤ V_{DD} I²C ≤ 2.2V, unless otherwise specified.

Symbol	Parameter	Conditions (Note 8)	LN	Units	
			Typical (Note 6)	Limits (Note 7)	(Limits)
t ₁	I ² C Clock Period			2.5	µs (min)
2	I ² C Data Setup Time			250	ns (min)
3	I ² C Data Stable Time			0	ns (min)
4	Start Condition Time			250	ns (min)
5	Stop Condition Time			250	ns (min)
6	I ² C Data Hold Time			250	ns (min)
/ _{IH}	I ² C Input Voltage High			0.7xV _{DD} I2C	V (min)
V _{IL}	I ² C Input Voltage Low			0.3xV _{DD} I ² C	V (max)

Note 1: All voltages are measured with respect to the GND pin unless other wise specified.

Note 2: Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is functional but do not guarantee specific performance limits. *Electrical Characteristics* state DC and AC electrical specifications under particular test conditions which guarantee specific performance limits. This assumes that the device is within the Operating Ratings. Specifications are not guaranteed for parameters where no limit is given, however, the typical value is a good indication of device performance.

Note 3: The maximum power dissipation must be derated at elevated temperatures and is dictated by T_{JMAX} , θ_{JA} , and the ambient temperature, T_A . The maximum allowable power dissipation is $P_{DMAX} = (T_{JMAX} - T_A)/\theta_{JA}$ or the number given in Absolute Maximum Ratings, whichever is lower. For the LM49100, see power derating currents for more information.

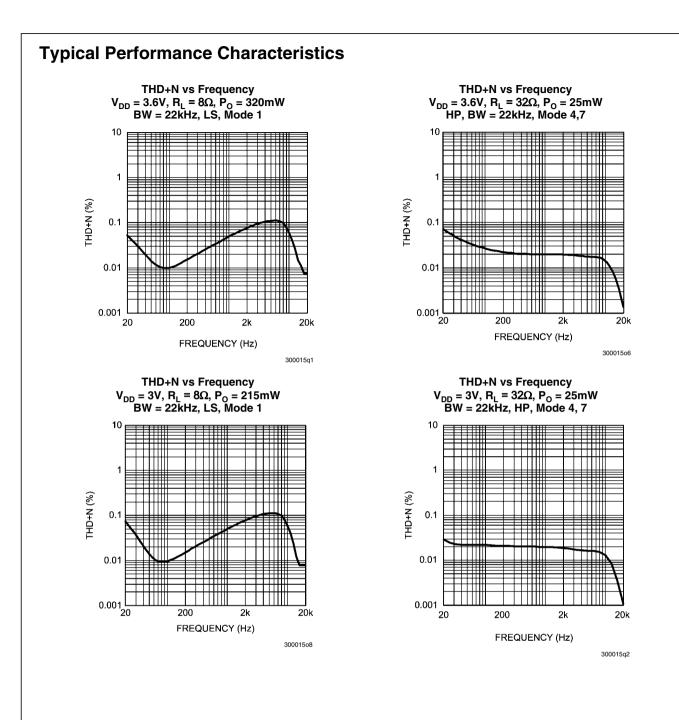
Note 4: Human body model, 100 pF discharged through a 1.5k $\!\Omega$ resistor.

Note 5: Machine Model, 220pF - 240pF discharged through all pins.

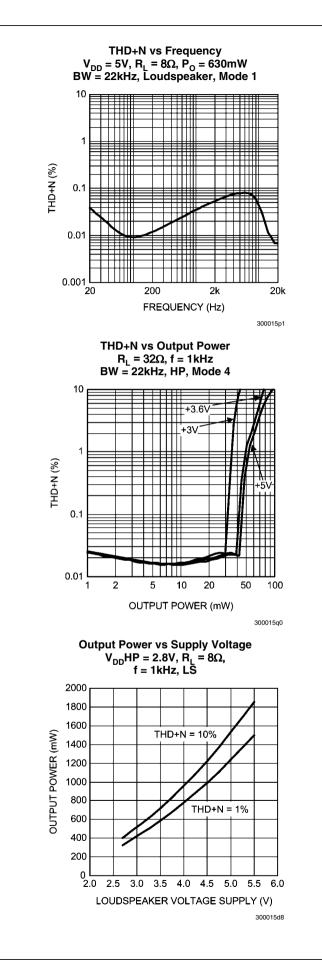
Note 6: Typicals are measured at 25°C and represent the parametric norm.

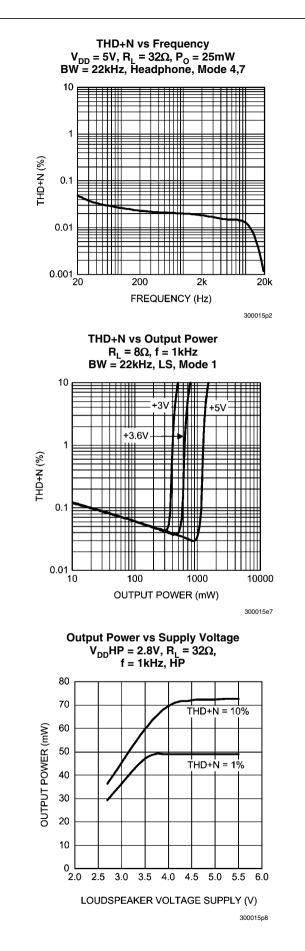
Note 7: Limits are guaranteed to National's AOQL (Average Outgoing Quality Level).

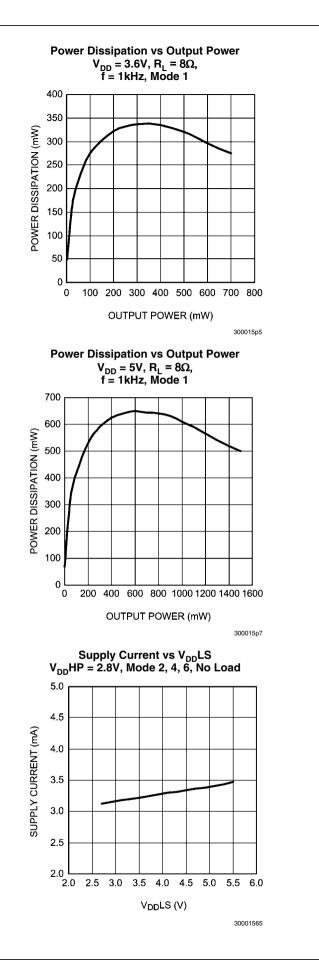
Note 8: Please refer to Figure 3 (I²C Timing Diagram).

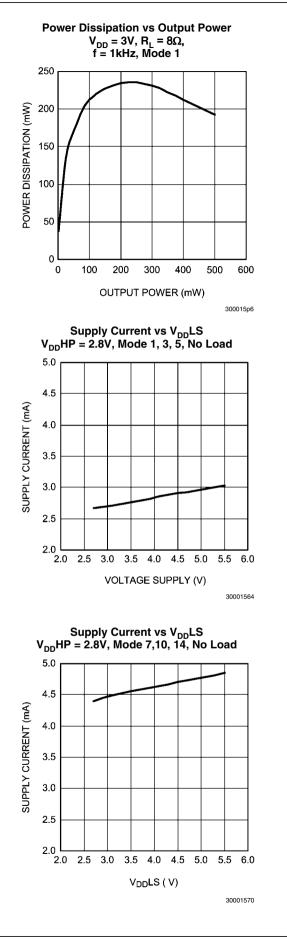


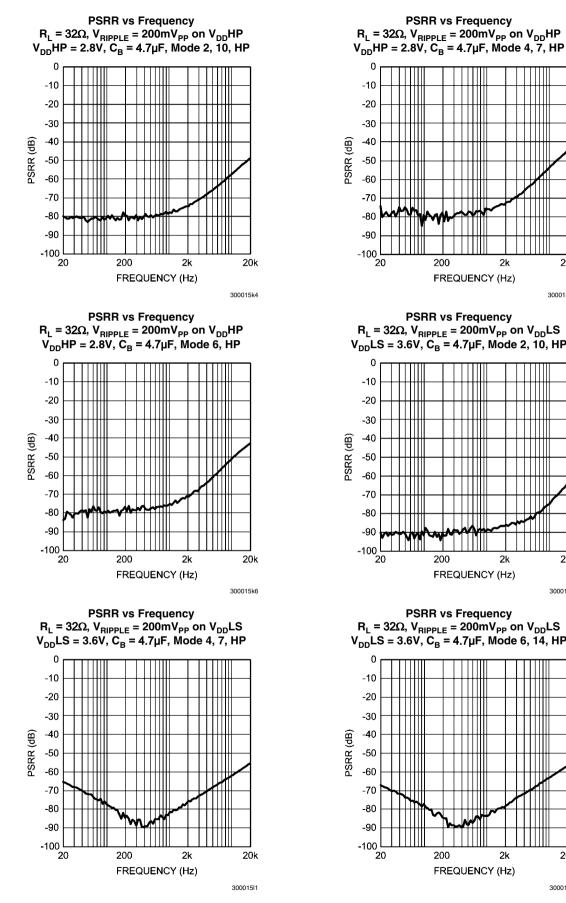


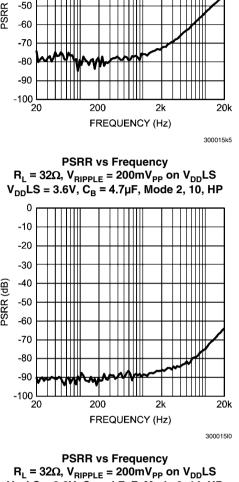


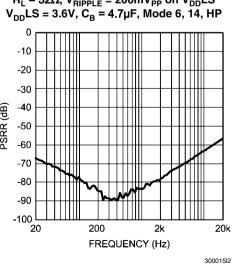


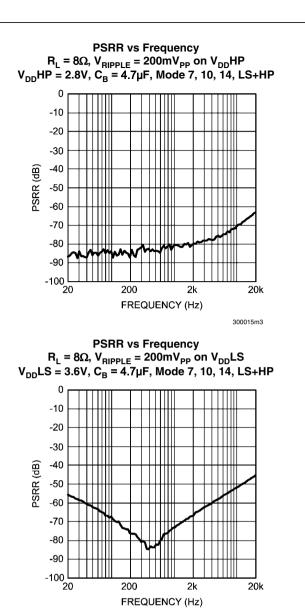


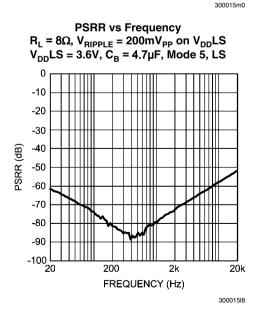


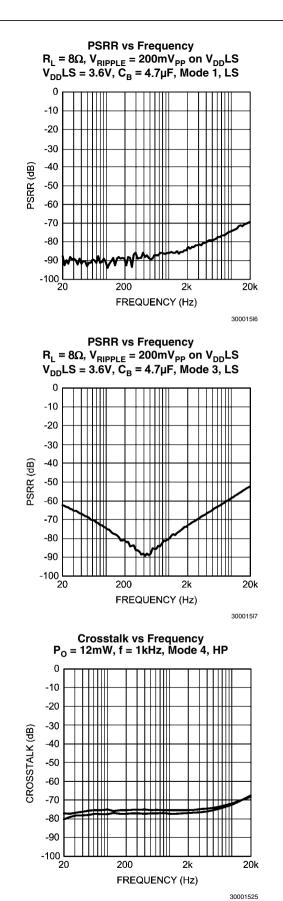












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LM49100 Control Tables

TABLE 1. I²C Control Register Table

The LM49100 is controlled through an I²C compatible interface. The I²C chip address is 0xF8 (ADR pin = 0) or 0xFAh (ADDR pin = 1).

	D7	D6	D5	D4	D3	D2	D1	D0
Modes Control	0	0	1	1	MC3	MC2	MC1	MC0
HP Volume (Gain) Control	0	1	INPUT_MU TE	0	0	HPR_SD	HPVC1	HPVC0
Mono Volume Control	1	0	0	MV4	MV3	MV2	MV1	MV0
Left Volume (Gain) Control	1	1	0	LV4	LV3	LV2	LV1	LV0
Right Volume (Gain) Control	1	1	1	RV4	RV3	RV2	RV1	RV0

TABLE 2. Headphone Attenuation Control

The following bits have added for extra headphone output attenuation:

Gain Select	HPVC1	HPVC0	Gain, dB
0	0	0	0
1	0	1	-12
2	1	0	-18
3	1	1	-24

TABLE 3. Output Mode Selection

Output Mode Number	мсз	MC2	MC1	МСО	Handsfree Mono Output	Right HP Output	Left HP Output	
0	0	0	0	0	SD	SD	SD	
1	0	0	0	1	$2 \times G_M \times M$	SD	SD	
2	0	0	1	0	SD	$G_{HP} \times (G_M \times M)$	$G_{HP} \times (G_M \times M)$	
3	0	0	1	1	$2 \times (G_L \times L + G_R \times R)$	SD	SD	
4	0	1	0	0	SD	$G_{HP} \times (G_R \times R)$	$G_{HP} \times (G_L \times L)$	
5	0	1	0	1	$2 \times (G_L \times L + G_R \times R + G_M \times M)$	SD	SD	
6	0	1	1	0	SD	$G_{HP} \times (G_R \times R + G_M \times M)$	$G_{HP} \times (G_L \times L + G_M \times M)$	
7	0	1	1	1	$2 \times (G_L \times L + G_R \times R)$	$G_{HP} \times (G_R \times R)$	$G_{HP} \times (G_L \times L)$	
10	1	0	1	0	$2 \times (G_L \times L + G_R \times R)$	$G_{HP} \times (G_M \times M)$	$G_{HP} \times (G_M \times M)$	
14	1	1	1	0	$2 \times (G_L \times L + G_R \times R)$	$G_{HP} \times (G_R \times R + G_M \times M)$	$\mathbf{G}_{HP} \times (\mathbf{G}_{L} \times L + \mathbf{G}_{M} \times M)$	

 G_L — Left channel gain G_R — Right channel gain G_M — Mono channel gain G_{HP} — Headphone Amplifier gain R— Right input signal

L — Left input signal SD — Shutdown

M — Mono input signal

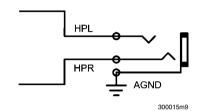
Volume Step	MV4/LV4/RV4	MV3/LV3/RV3	MV2/LV2/RV2	MV1/LV1/RV1	MV0/LV0/RV0	R/L Gain, dB	MonoGain, dB
1	0	0	0	0	0	-54	-60
2	0	0	0	0	1	-47	-53
3	0	0	0	1	0	-40.5	-46.5
4	0	0	0	1	1	-34.5	-40.5
5	0	0	1	0	0	-30.0	-36
6	0	0	1	0	1	-27	-33
7	0	0	1	1	0	-24	-30
8	0	0	1	1	1	-21	-27
9	0	1	0	0	0	-18	-24
10	0	1	0	0	1	-15	-21
11	0	1	0	1	0	-13.5	-19.5
12	0	1	0	1	1	-12	-18
13	0	1	1	0	0	-10.5	-16.5
14	0	1	1	0	1	-9	–15
15	0	1	1	1	0	-7.5	-13.5
16	0	1	1	1	1	-6	-12
17	1	0	0	0	0	-4.5	-10.5
18	1	0	0	0	1	-3	-9
19	1	0	0	1	0	-1.5	-7.5
20	1	0	0	1	1	0	-6
21	1	0	1	0	0	1.5	-4.5
22	1	0	1	0	1	3	-3
23	1	0	1	1	0	4.5	-1.5
24	1	0	1	1	1	6	0
25	1	1	0	0	0	7.5	1.5
26	1	1	0	0	1	9	3
27	1	1	0	1	0	10.5	4.5
28	1	1	0	1	1	12	6
29	1	1	1	0	0	13.5	7.5
30	1	1	1	0	1	15	9
31	1	1	1	1	0	16.5	10.5
32	1	1	1	1	1	18	12

Application Information MINIMIZING CLICK AND POP

To minimize the audible click and pop heard through a headphone, maximize the input signal through the corresponding volume (gain) control registers and adjust the output amplifier gain accordingly to achieve the user's desired signal gain. For example, setting the output of the headphone amplifier to -24dB and setting the input volume control gain to 24dB will reduce the output offset from 7mV (typical) to 2.2mV (typical). This will reduce the audible click and pop noise significantly while maintaining a 0dB signal gain.

SIGNAL GROUND NOISE

The LM49100 has proprietary suppression circuitry, which provides an additional -50dB (typical) attenuation of the headphone ground noise and its incursion into the headphone. For optimum utilization of this feature the headphone jack ground should connect to the AGND (E3) bump.



I²C PIN DESCRIPTION

SDA: This is the serial data input pin. SCL: This is the clock input pin. ADDR: This is the address select input pin.

I²C COMPATIBLE INTERFACE

The LM49100 uses a serial bus which conforms to the I²C protocol to control the chip's functions with two wires: clock (SCL) and data (SDA). The clock line is uni-directional. The data line is bi-directional (open-collector). The LM49100's I²C compatible interface supports standard (100kHz) and fast (400kHz) I²C modes. In this discussion, the master is the controlling microcontroller and the slave is the LM49100.

The I^2C address for the LM49100 is determined using the ADDR pin. The LM49100's two possible I^2C chip addresses

are of the form 111110X₁0 (binary), where $X_1 = 0$, if ADDR pin is logic LOW; and $X_1 = 1$, if ADDR pin is logic HIGH. If the I²C interface is used to address a number of chips in a system, the LM49100's chip address can be changed to avoid any possible address conflicts.

The bus format for the I²C interface is shown in Figure 2. The bus format diagram is broken up into six major sections:

The "start" signal is generated by lowering the data signal while the clock signal is HIGH. The start signal will alert all devices attached to the I²C bus to check the incoming address against their own address.

The 8-bit chip address is sent next, most significant bit first. The data is latched in on the rising edge of the clock. Each address bit must be stable while the clock level is HIGH.

After the last bit of the address bit is sent, the master releases the data line HIGH (through a pull-up resistor). Then the master sends an acknowledge clock pulse. If the LM49100 has received the address correctly, then it holds the data line LOW during the clock pulse. If the data line is not held LOW during the acknowledge clock pulse, then the master should abort the rest of the data transfer to the LM49100.

The 8 bits of data are sent next, most significant bit first. Each data bit should be valid while the clock level is stable HIGH.

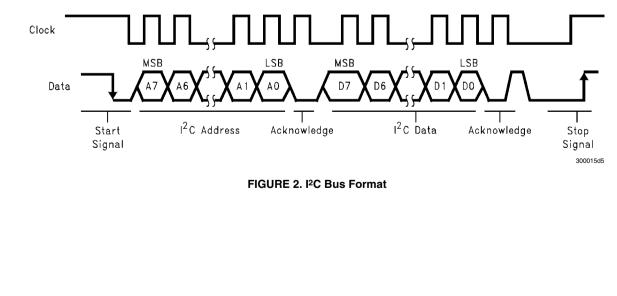
After the data byte is sent, the master must check for another acknowledge to see if the LM49100 received the data.

If the master has more data bytes to send to the LM49100, then the master can repeat the previous two steps until all data bytes have been sent.

The "stop" signal ends the transfer. To signal "stop", the data signal goes HIGH while the clock signal is HIGH. The data line should be held HIGH when not in use.

I²C INTERFACE POWER SUPPLY PIN (V_{DD}I²C)

The LM49100's I²C interface is powered up through theV_{DD} I²C pin. The LM49100's I²C interface operates at a voltage level set by the V_{DD} I²C pin which can be set independent to that of the main power supply pin V_{DD}. This is ideal whenever logic levels for the I²C interface are dictated by a microcontroller or microprocessor that is operating at a lower supply voltage than the main battery of a portable system.



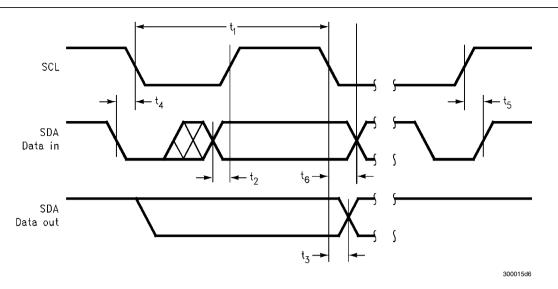


FIGURE 3. I²C Timing Diagram

PCB LAYOUT AND SUPPLY REGULATION CONSIDERATIONS FOR DRIVING 8Ω LOAD

Power dissipated by a load is a function of the voltage swing across the load and the load's impedance. As load impedance decreases, load dissipation becomes increasingly dependent on the interconnect (PCB trace and wire) resistance between the amplifier output pins and the load's connections. Residual trace resistance causes a voltage drop, which results in power dissipated in the trace and not in the load as desired. For example, 0.1 Ω trace resistance reduces the output power dissipated by an 8 Ω load from 158.3mW to 156.4mW. The problem of decreased load dissipation is exacerbated as load impedance decreases. Therefore, to maintain the highest load dissipation and widest output voltage swing, PCB traces that connect the output pins to a load must be as wide as possible.

Poor power supply regulation adversely affects maximum output power. A poorly regulated supply's output voltage decreases with increasing load current. Reduced supply voltage causes decreased headroom, output signal clipping, and reduced output power. Even with tightly regulated supplies, trace resistance creates the same effects as poor supply regulation. Therefore, making the power supply traces as wide as possible helps maintain full output voltage swing.

BRIDGE CONFIGURATION EXPLANATION

The LM49100 drives a load, such as a loudspeaker, connected between outputs, LS+ and LS-.

This results in both amplifiers producing signals identical in magnitude, but 180° out of phase. Taking advantage of this phase difference, a load is placed between LS- and LS+ and driven differentially (commonly referred to as "bridge mode").

Bridge mode amplifiers are different from single-ended amplifiers that drive loads connected between a single amplifier's output and ground. For a given supply voltage, bridge mode has a distinct advantage over the single-ended configuration: its differential output doubles the voltage swing across the load. Theoretically, this produces four times the output power when compared to a single-ended amplifier under the same conditions. This increase in attainable output power assumes that the amplifier is not current limited and that the output signal is not clipped. Another advantage of the differential bridge output is no net DC voltage across the load. This is accomplished by biasing LS- and LS+ outputs at half-supply. This eliminates the coupling capacitor that single supply, single-ended amplifiers require. Eliminating an output coupling capacitor in a typical single-ended configuration forces a single-supply amplifier's half-supply bias voltage across the load. This increases internal IC power dissipation and may permanently damage loads such as loudspeakers.

POWER DISSIPATION

Power dissipation is a major concern when designing a successful single-ended or bridged amplifier.

A direct consequence of the increased power delivered to the load by a bridge amplifier is higher internal power dissipation. The LM49100 has a pair of bridged-tied amplifiers driving a handsfree loudspeaker, LS. The maximum internal power dissipation operating in the bridge mode is twice that of a single-ended amplifier. From Equation (1), assuming a 5V power supply and an 8Ω load, the maximum MONO power dissipation is 634mW.

$$P_{\text{DMAX-IS}} = 4(V_{\text{DD}})^2 I (2\pi^2 R_{\text{I}}): \text{Bridge Mode}$$
(1)

The LM49100 also has a pair of single-ended amplifiers driving stereo headphones, HPR and HPL. The maximum internal power dissipation for HPR and HPL is given by equation (2). Assuming a 2.8V power supply and a 32 Ω load, the maximum power dissipation for L_{OUT} and R_{OUT} is 49mW, or 99mW total.

$$P_{DMAX-HPL} = 4(V_{DD}HP)^2 / (2\pi^2 R_L)$$
: Single-ended Mode (2)

The maximum internal power dissipation of the LM49100 occurs when all three amplifiers pairs are simultaneously on; and is given by Equation (3).

$$P_{DMAX-TOTAL} = P_{DMAX-LS} + P_{DMAX-HPL} + P_{DMAX-HPR}$$
(3)

The maximum power dissipation point given by Equation (3) must not exceed the power dissipation given by Equation (4):

$$\mathsf{P}_{\mathsf{DMAX}} = (\mathsf{T}_{\mathsf{JMAX}} - \mathsf{T}_{\mathsf{A}}) / \theta_{\mathsf{JA}}$$

(4)

The LM49100's T_{JMAX} = 150°C. In the GR package, the LM49100's θ_{JA} is 50.2°C/W. At any given ambient temperature T_A, use Equation (4) to find the maximum internal power dissipation supported by the IC packaging. Rearranging Equation (4) and substituting P_{DMAX-TOTAL} for P_{DMAX} results in Equation (5). This equation gives the maximum ambient temperature that still allows maximum stereo power dissipation temperature.

$$T_{A} = T_{JMAX} - P_{DMAX-TOTAL} \theta_{JA}$$
(5)

For a typical application with a 5V power supply and an 8Ω load, the maximum ambient temperature that allows maximum mono power dissipation without exceeding the maximum junction temperature is approximately 114°C for the GR package.

$$T_{JMAX} = P_{DMAX-TOTAL} \theta_{JA} + T_A$$
(6)

Equation (6) gives the maximum junction temperature T_{JMAX} . If the result violates the LM49100's 150°C, reduce the maximum junction temperature by reducing the power supply voltage or increasing the load resistance. Further allowance should be made for increased ambient temperatures.

The above examples assume that a device is a surface mount part operating around the maximum power dissipation point. Since internal power dissipation is a function of output power, higher ambient temperatures are allowed as output power or duty cycle decreases. If the result of Equation (3) is greater than that of Equation (4), then decrease the supply voltage, increase the load impedance, or reduce the ambient temperature. If these measures are insufficient, a heat sink can be added to reduce θ_{JA} . The heat sink can be created using additional copper area around the package, with connections to the ground pin(s), supply pin and amplifier output pins.

POWER SUPPLY BYPASSING

As with any power amplifier, proper supply bypassing is critical for low noise performance and high power supply rejection. Applications that employ a 5V regulator typically use a 1μ F in parallel with a 0.1μ F filter capacitors to stabilize the regulator's output, reduce noise on the supply line, and improve the supply's transient response. However, their presence does not eliminate the need for a local 4.7μ F tantalum bypass capacitor and a parallel 0.1μ F ceramic capacitor connected between the LM49100's supply pin and ground. Keep the length of leads and traces that connect capacitors between the LM49100's power supply pin and ground as short as possible.

SELECTING EXTERNAL COMPONENTS

Input Capacitor Value Selection

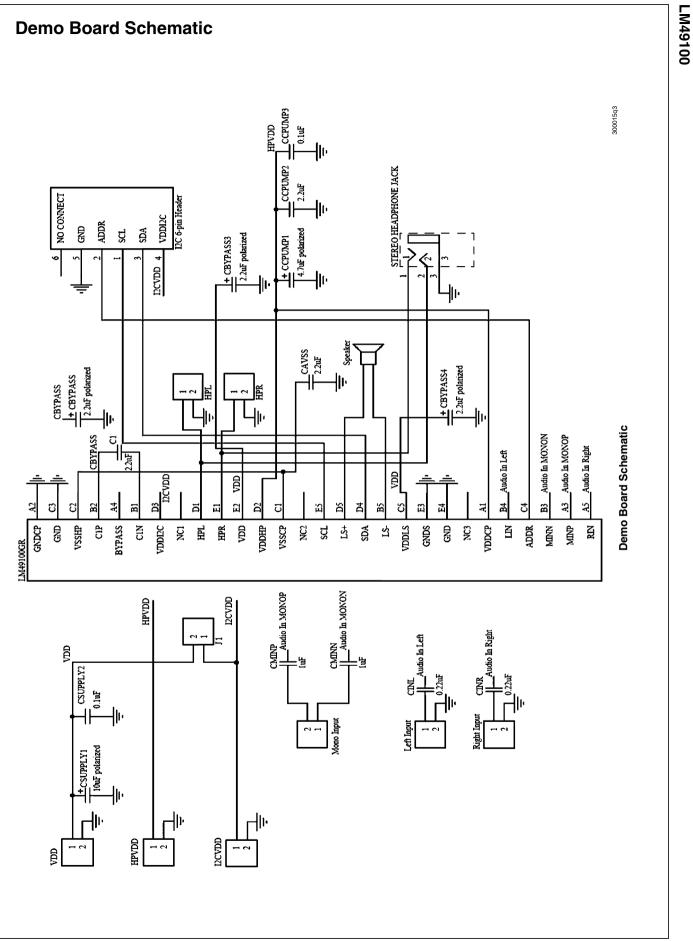
Amplifying the lowest audio frequencies requires high value input coupling capacitor ($C_{\rm IN}$ in Figure 1). A high value capacitor can be expensive and may compromise space efficiency in portable designs. In many cases, however, the loudspeakers used in portable systems, whether internal or external, have little ability to reproduce signals below 150Hz. Applications using loudspeakers and headphones with this limited frequency response reap little improvement by using large input capacitor.

The internal input resistor (R_i), typical 12.5k Ω , and the input capacitor (C_{IN}) produce a high pass filter cutoff frequency that is found using Equation (7).

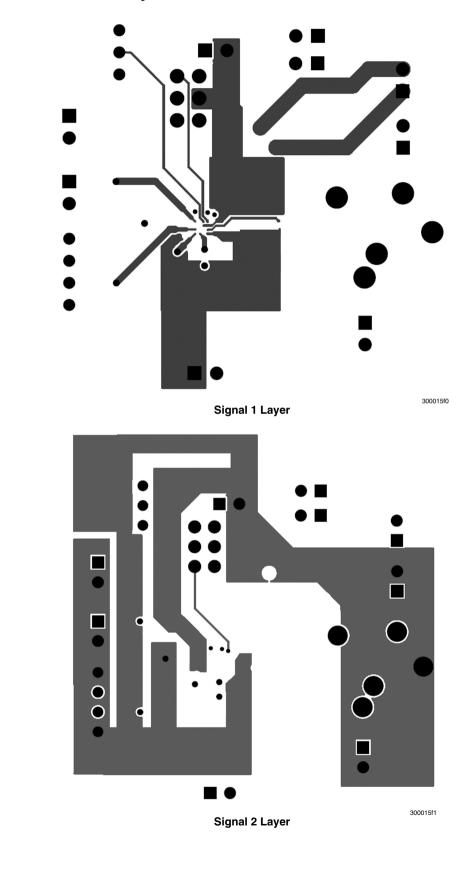
$$f_{c} = 1 / (2\pi R_{i}C_{IN})$$
 (7)

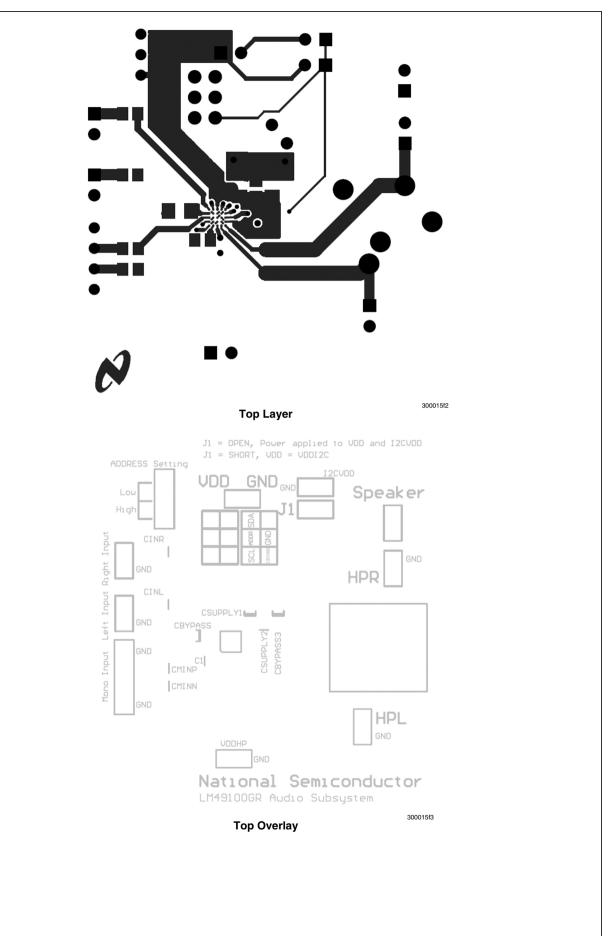
Bypass Capacitor Value Selection

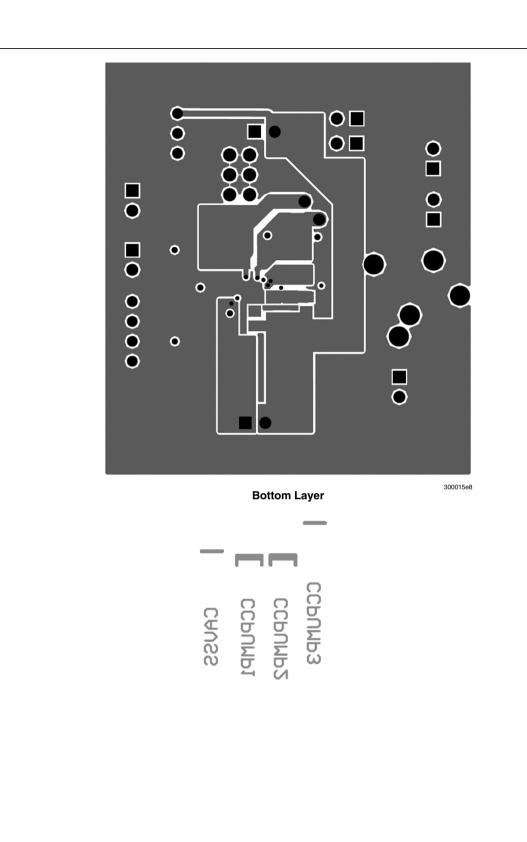
Besides minimizing the input capacitor size, careful consideration should be paid to value of $C_{\rm B}$, the capacitor connected to the BYPASS pin. Since $C_{\rm B}$ determines how fast the LM49100 settles to quiescent operation, its value is critical when minimizing turn-on pops. Choosing $C_{\rm B}$ equal to $2.2\mu{\rm F}$ along with a small value of $C_{\rm i}$ (in the range of $0.1\mu{\rm F}$ to $0.33\mu{\rm F}$), produces a click-less and pop-less shutdown function. As discussed above, choosing $C_{\rm IN}$ no larger than necessary for the desired bandwidth helps minimize clicks and pops. $C_{\rm B}$'s value should be in the range of 4 to 5 times the value of $C_{\rm IN}$. This ensures that output transients are eliminated when power is first applied or the LM49100 resumes operation after shutdown.



Demonstration Board Layout







551013056-001 Rev. A

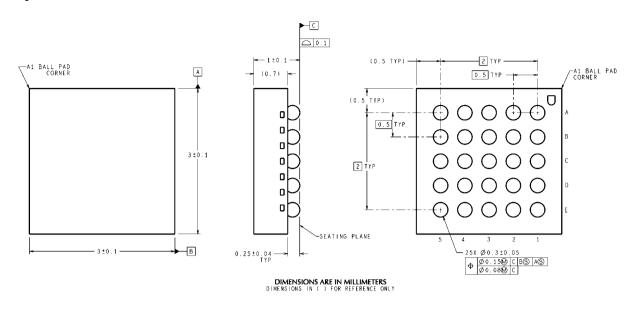
Bottom Overlay

Revision History

Rev	Date	Description
1.0	06/21/07	Initial release.
1.1	06/28/07	Changed the mktg outline from TLA25XXX to GRA25A.
1.2	08/09/07	Replaced some curves.
1.3	08/13/07	Changed the $f = 1kHz$ into $f = 217Hz$ (PSRR) in the Electrical Characteristics table.
1.4	08/14/07	Edited Table 1.
1.5	09/18/07	Edited the schematic diagram.

Physical Dimensions inches (millimeters) unless otherwise noted

LM49100



GRA25A (Rev A)

Dimensions: $X_1 = X_2 = 3 \text{ mm}$, $X_3 = 1 \text{ mm}$ GR Package Order Number LM49100GR See NS Package Number GRA25A

Notes

Notes

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